LAMP0504MF

Rev.F Mar.-2016

Low Capacitance TVS Array in a SOT23-6 Plastic Package.

Small package saves board space Protects up to four I/O lines & power line Low capacitance for high-speed interfaces Low leakage current and clamping voltage Low operating voltage.

ώ̣ ᶏ ᴟ Ặ / Absolute Maximum Ratings(Ta=25 ɹ)

Parameter	Symbol	Rating	Unit
Peak Pulse Power (tp = 8/20μs)	PPP	150	W
Peak Pulse Current (tp = 8/20μs)	IPP	6	A
ESD per IEC 61000-4-2 (Air)	VESD 1 IEC 61000-4-2 (Air)	±15	kV
ESD per IEC 61000-4-2 (Contact)	VESD 2 IEC 61000-4-2 (Contact)	±8	kV
Operating Temperature	TOPR	-55 to 125	
Storage Temperature	TSTG	-55 to 150	

꞊ ㅅ ᴟ Ặ / Electrical Characteristics(Ta=25 ɹ)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Stand-Off Voltage	V_{RWM}	Pin 5 to GND			5	V
Reverse Breakdown Voltage	V_{BR}	Pin 5 to GND It=1mA	6			V
Reverse Leakage Current	I_R	V_{RWM}=5V T=25 Pin 5 to GND			2	μA
Clamping Voltage	V_C	I_{PP}=1A tp=8/20μs Any I/O pin to GND		8.5	12	V
Junction Capacitance	C_{J1}	V_R=0V f=1MHz Any I/O pin to GND			3	pF
Junction Capacitance	C_{J2}	V_R=0V f=1MHz Between I/O pins			1.5	pF

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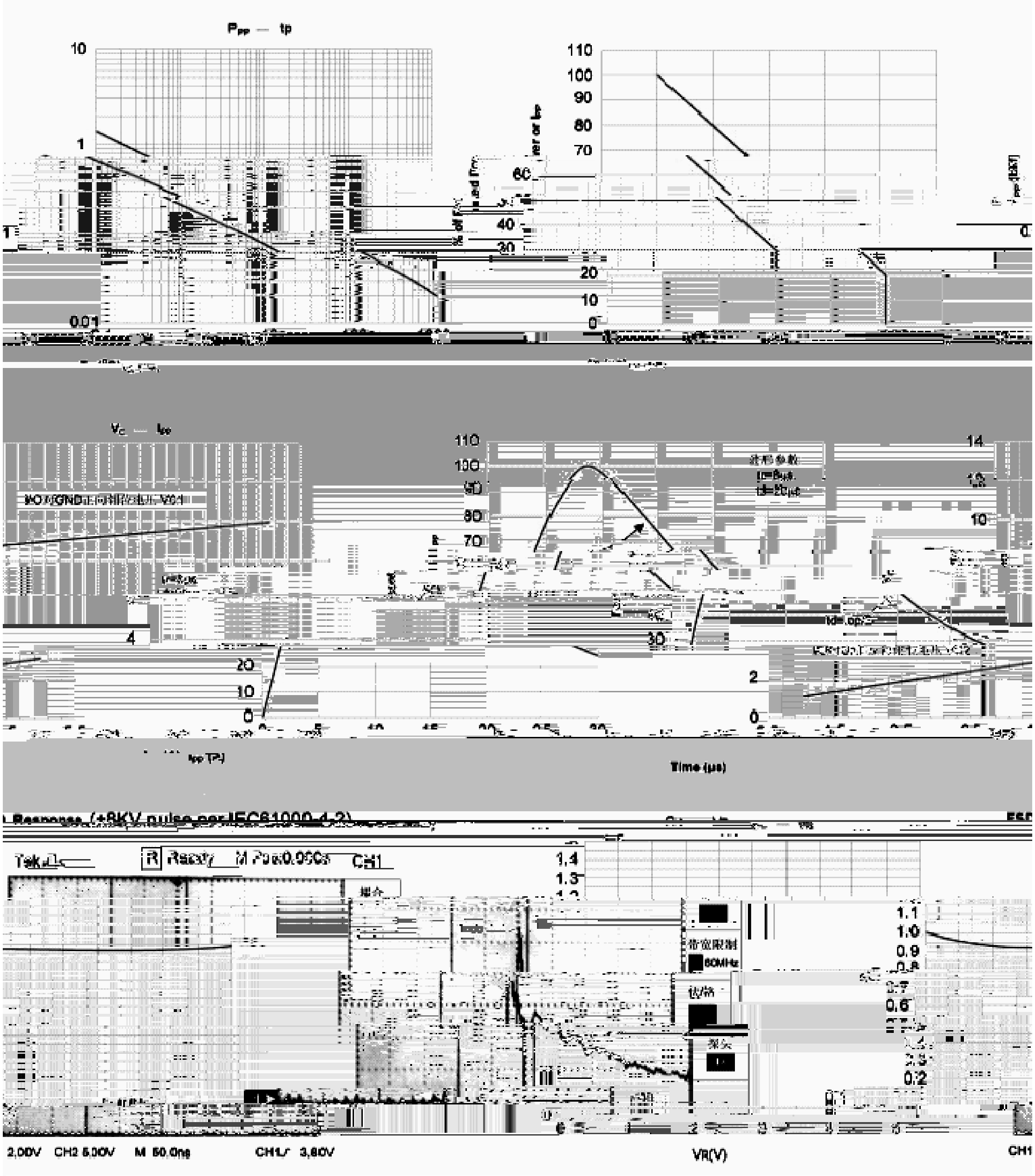

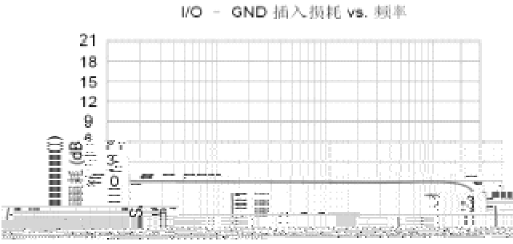

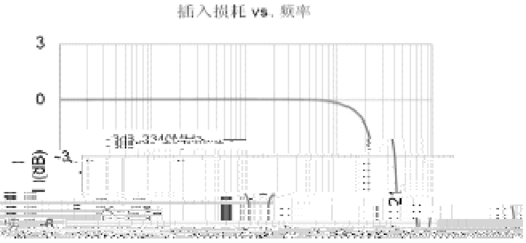

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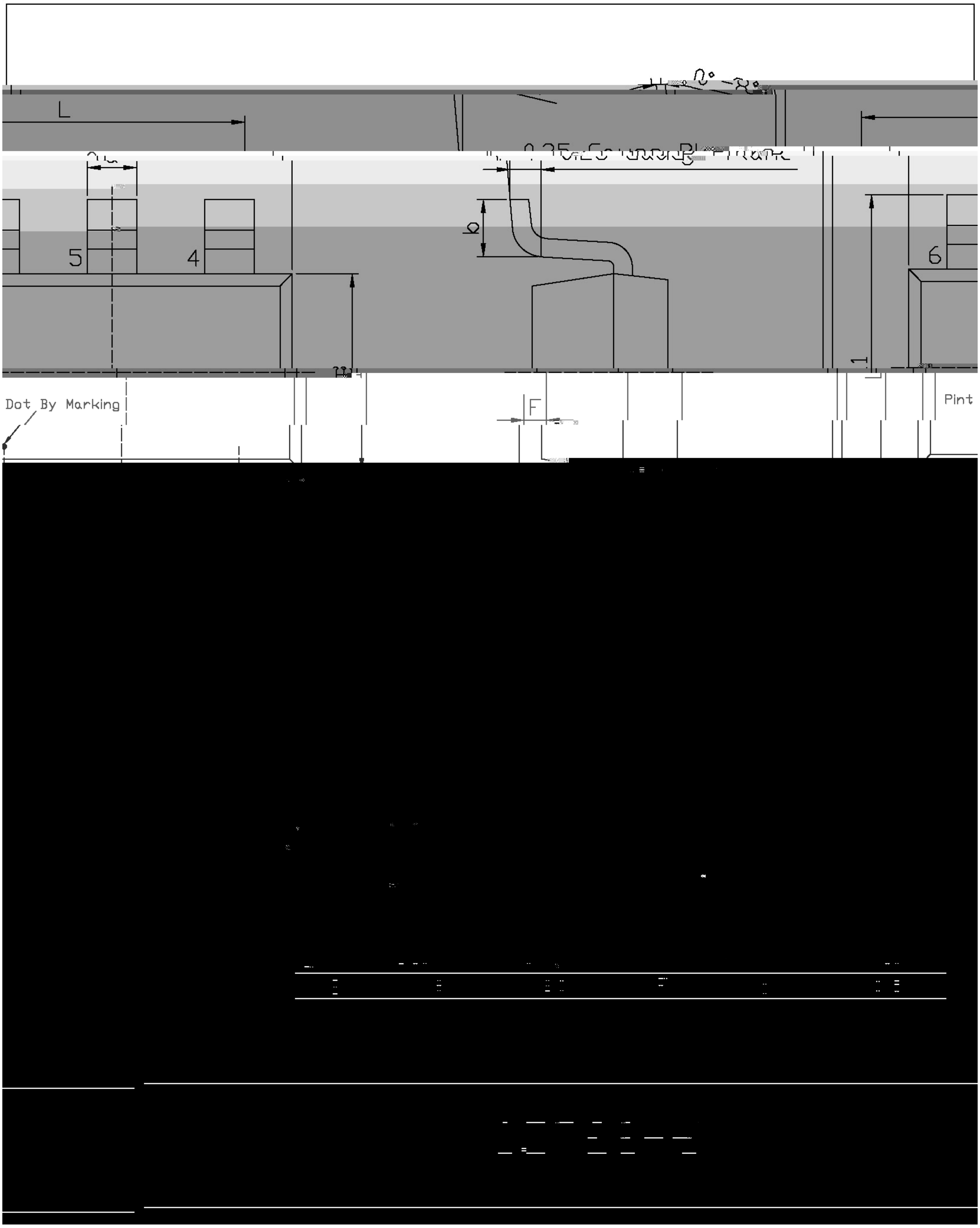

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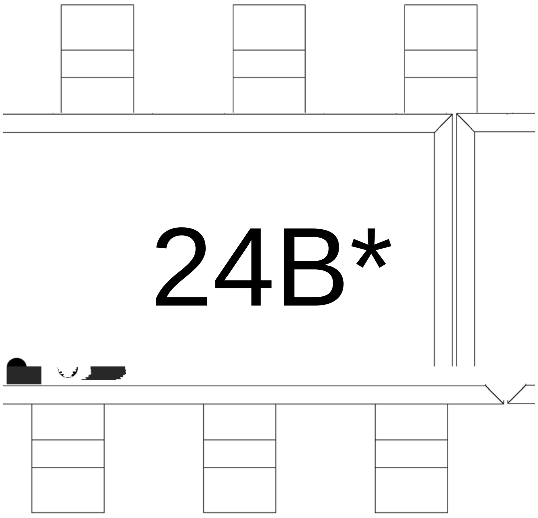

Note:

24B:	Product Type Code
*:	Lot No. Code, code change with Lot No.

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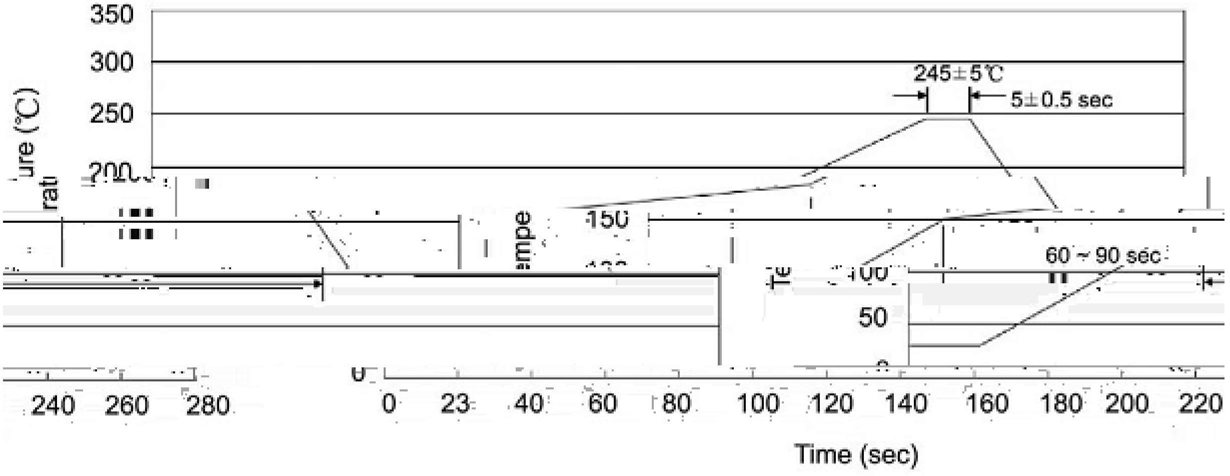

	Note:
1 25 150 60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2 245 5 5 0.5sec;	2.Peak Temp.:245 5 , Duration:5 0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

ˀ ü q ̄ `Y Ţ / Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260 5 Time:10 1 sec

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/ REEL

Package Type	Units					Dimension (unit mm^3)		

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